



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-12-04
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	C207*T33PB6F	A	Z8GA	2013-12-04
Amount	UoM	Unit type	ST ECOPACK Grade	
80.061	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	12	gull wing	
Comment	Package: SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	C207*T33P86F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other Inorganic Material	2.909	mg	Supplier	Silicon die	Silicon	7440-21-3		2.85	mg	979718	35598
Silicon Die				Supplier	Metallization	Titanium (Ti)	7440-32-6		0.019	mg	6531	237
Silicon Die				Supplier	Metallization	Tungsten (W)	7440-33-7		0.004	mg	1375	50
Silicon Die				Supplier	Passivation	Silicon Oxide(SiO2)	7631-86-9		0.012	mg	4125	150
Silicon Die				Supplier	Back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	344	12
Silicon Die				Supplier	Back side metallization	Gold (Au)	7440-57-5		0.004	mg	1375	50
Silicon Die				Supplier	Back side metallization	Nickel (Ni)	7440-02-0		0.019	mg	6531	237
Leadframe	Copper and its alloy	31.929	mg	Supplier	Alloy	Copper(CU)	7440-50-8		30.875	mg	966989	385643
Leadframe				Supplier	Alloy	Iron(Fe)	7439-89-6		0.745	mg	23333	9305
Leadframe				Supplier	Alloy	Phosphorus(P)	7723-14-0		0.026	mg	814	325
Leadframe				Supplier	Alloy	Zinc(Zn)	7440-66-6		0.04	mg	1253	500
Leadframe				Supplier	Alloy	Silver(Ag)	7440-22-4		0.243	mg	7611	3035
Die Attach	Other Organic Material	1.365	mg	Supplier	Glue	Silver(Ag)	7440-22-4		1.194	mg	874725	14914
Die Attach				Supplier	Glue	isobornyl Methacrylate	7534-94-3		0.082	mg	60073	1024
Die Attach				Supplier	Glue	Maleimides	Proprietary		0.082	mg	60073	1024
Die Attach				Supplier	Glue	Polymer	Proprietary		0.007	mg	5128	87
Bonding wire	Other Inorganic Material	0.337	mg	Supplier	Bonding wire	Copper(CU)	7440-50-8		0.337	mg	1000000	4209
Encapsulation	Other Organic Material	39.718	mg	Supplier	Molding compound	Silica Fused	60676-86-0		30.98	mg	779999	386955
Encapsulation				Supplier	Molding compound	Solid Epoxy Resin	Proprietary		4.369	mg	110001	54571
Encapsulation				Supplier	Molding compound	Phenol Resin	Proprietary		4.369	mg	110001	54571
Finishing	Other Inorganic Material	3.803	mg	Supplier	Connection Coating	Tin(Sn)	7440-31-5		3.803	mg	1000000	47501